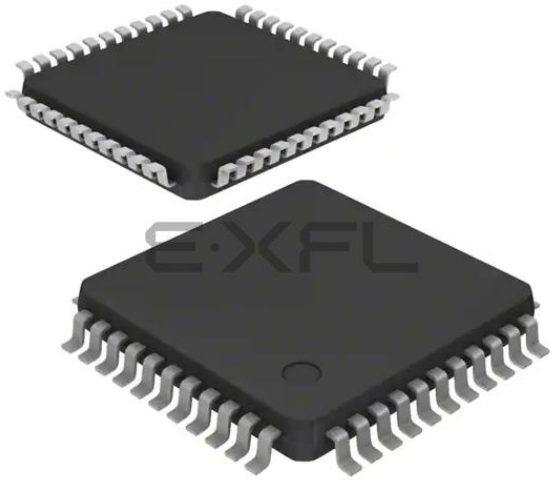

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	4KB (4K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e4016fec00tr

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

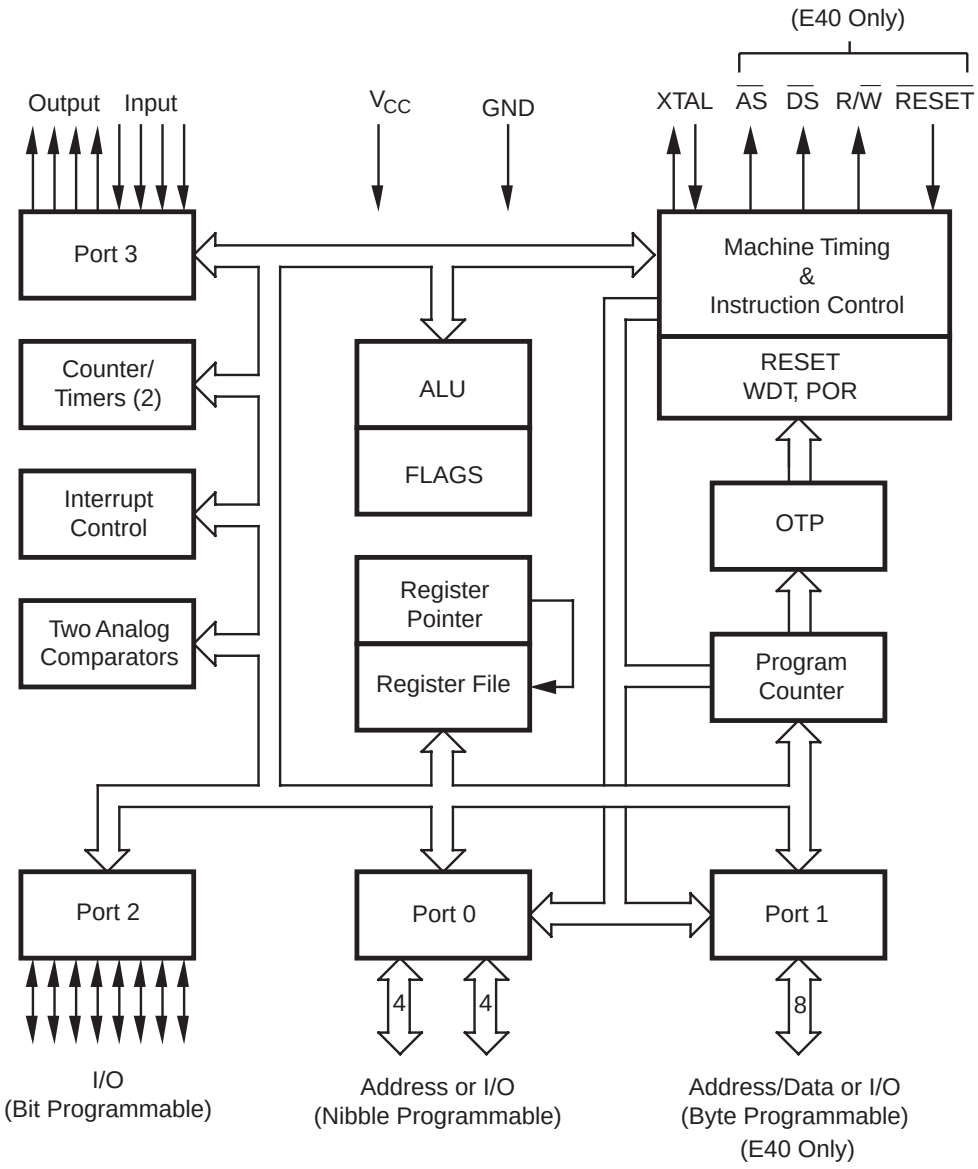


Figure 1. Z86E30/E31/E40 Functional Block Diagram

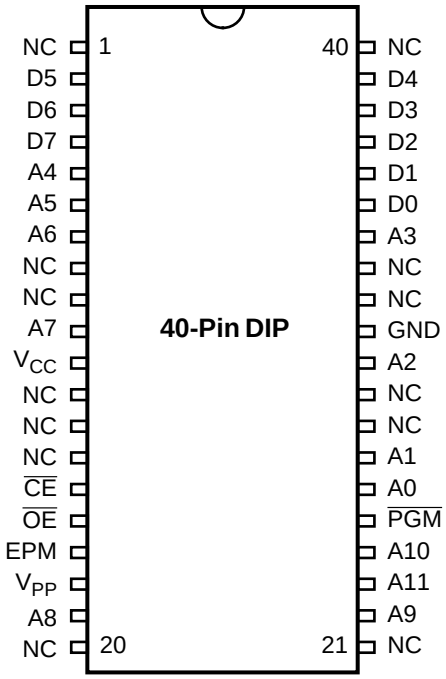


Figure 6. 40-Pin DIP Pin Configuration EPROM Mode

Table 4. 40-Pin DIP Package Pin Identification EPROM Mode

Pin #	Symbol	Function	Direction
1	NC	No Connection	
2–4	D5–D7	Data 5,6,7	In/Output
5–7	A4–A6	Address 4,5,6	Input
8–9	NC	No Connection	
10	A7	Address 7	Input
11	V_{CC}	Power Supply	
12–14	NC	No Connection	
15	$\overline{CE}$	Chip Select	Input
16	$\overline{OE}$	Output Enable	Input
17	EPM	EPROM Prog. Mode	Input
18	V_{PP}	Prog. Voltage	Input
19	A8	Address 8	Input
20–21	NC	No Connection	
22	A9	Address 9	Input
23	A11	Address 11	Input
24	A10	Address 10	Input
25	$\overline{PGM}$	Prog. Mode	Input
26–27	A0–A1	Address 0,1	Input
28–29	NC	No Connection	
30	A2	Address 2	Input
31	GND	Ground	
32–33	NC	No Connection	
34	A3	Address 3	Input
35–39	D0–D4	Data 0,1,2,3,4	In/Output
40	NC	No Connection	

PIN IDENTIFICATION (Continued)

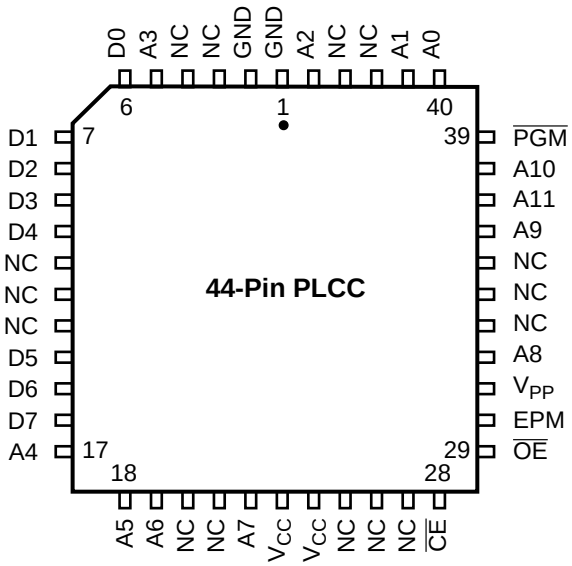


Figure 7. 44-Pin PLCC Pin Configuration EPROM Programming Mode

Table 5. 44-Pin PLCC Pin Configuration EPROM Programming Mode

Pin #	Symbol	Function	Direction
1–2	GND	Ground	
3–4	NC	No Connection	
5	A3	Address 3	Input
6–10	D0–D4	Data 0,1,2,3,4	In/Output
11–13	NC	No Connection	
14–16	D5–D7	Data 5,6,7	In/Output
17–19	A4–A6	Address 4,5,6	Input
20–21	NC	No Connection	
22	A7	Address 7	Input
23–24	V_{CC}	Power Supply	
25–27	NC	No Connection	
28	$\overline{CE}$	Chip Select	Input
29	$\overline{OE}$	Output Enable	Input
30	EPM	EPROM Prog. Mode	Input

Table 5. 44-Pin PLCC Pin Configuration EPROM Programming Mode

Pin #	Symbol	Function	Direction
31	V_{PP}	Prog. Voltage	Input
32	A8	Address 8	Input
33–35	NC	No Connection	
36	A9	Address 9	Input
37	A11	Address 11	Input
38	A10	Address 10	Input
39	$\overline{PGM}$	Prog. Mode	Input
40–41	A0,A1	Address 0,1	Input
42–43	NC	No Connection	
44	A2	Address 2	Input

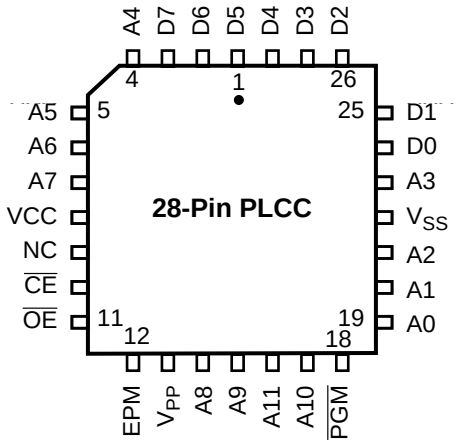


Figure 12. EPROM Programming Mode 28-Pin PLCC Pin Configuration

Table 8. 28-Pin EPROM Pin Identification

Pin #	Symbol	Function	Direction
1–3	D5–D7	Data 5,6,7	In/Output
4–7	A4–A7	Address 4,5,6,7	Input
8	V_{CC}	Power Supply	
9	NC	No connection	
10	$\overline{CE}$	Chip Select	Input
11	$\overline{OE}$	Output Enable	Input
12	EPM	EPROM Prog. Mode	Input
13	V_{PP}	Prog. Voltage	Input
14–15	A8–A9	Address 8,9	Input
16	A11	Address 11	Input
17	A10	Address 10	Input
18	$\overline{PGM}$	Prog. Mode	Input
19–21	A0–A2	Address 0,1,2	Input
22	V_{SS}	Ground	
23	A3	Address 3	Input
24–28	D0–D4	Data 0,1,2,3,4	In/Output

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units
Ambient Temperature under Bias	–40	+105	C
Storage Temperature	–65	+150	C
Voltage on any Pin with Respect to V_{SS} [Note 1]	–0.6	+7	V
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V
Voltage on XTAL1 and $\overline{\text{RESET}}$ Pins with Respect to V_{SS} [Note 2]	–0.6	V_{DD}+1	V
Total Power Dissipation		1.21	W
Maximum Allowable Current out of V_{SS}		220	mA
Maximum Allowable Current into V_{DD}		180	mA
Maximum Allowable Current into an Input Pin [Note 3]	–600	+600	µA
Maximum Allowable Current into an Open-Drain Pin [Note 4]	–600	+600	µA
Maximum Allowable Output Current Sinked by Any I/O Pin		25	mA
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA
Maximum Allowable Output Current Sinked by $\overline{\text{RESET}}$ Pin		3 mA	

Notes:
1. This applies to all pins except XTAL pins and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. This excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

Total power dissipation should not exceed 1.2 W for the package. Power dissipation is calculated as follows:

Total Power Dissipation = V_{DD} x [I_{DD} – (sum of I_{OH})]
+ sum of [(V_{DD} – V_{OH}) x I_{OH}]
+ sum of (V_{0L} x I_{0L})

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Test Load).

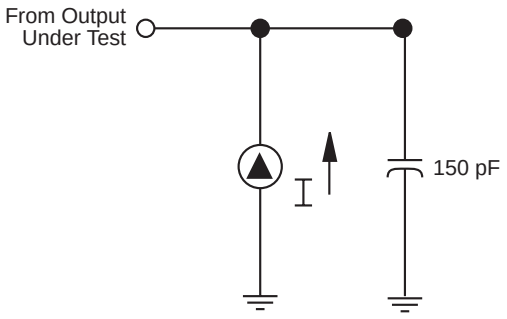


Figure 13. Test Load Diagram

Sym	Parameter	V_{CC} Note [3]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
			T_A=–40 °C to +105 °C					
V_{CH}	Clock Input High Voltage	4.5V 5.5V	0.7 V_{CC} 0.7 V_{CC}	V_{CC}+0.3 V_{CC}+0.3	2.5 2.5	V V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	4.5V 5.5V	GND-0.3 GND-0.3	0.2 V_{CC} 0.2 V_{CC}	1.5 1.5	V V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	4.5V 5.5V	0.7 V_{CC} 0.7 V_{CC}	V_{CC}+0.3 V_{CC}+0.3	2.5 2.5	V V		
V_{IL}	Input Low Voltage	4.5V 5.5V	GND-0.3 GND-0.3	0.2 V_{CC} 0.2 V_{CC}	1.5 1.5	V V		
V_{OH}	Output High Voltage Low EMI Mode	4.5V 5.5V	V_{CC} -0.4 V_{CC} -0.4		4.8 4.8	V V	I_{OH} = – 0.5 mA I_{OH} = – 0.5 mA	8 8
V_{OH1}	Output High Voltage	4.5V 4.5V	V_{CC} -0.4 V_{CC} -0.4		4.8 4.8	V V	I_{OH} = -2.0 mA I_{OH} = -2.0 mA	8 8
V_{OL}	Output Low Voltage Low EMI Mode	4.5V 5.5V		0.4 0.4	0.2 0.2	V V	I_{OL} = 1.0 mA I_{OL} = 1.0 mA	
V_{OL1}	Output Low Voltage	4.5V 5.5V		0.4 0.4	0.1 0.1	V V	I_{OL} = + 4.0 mA I_{OL} = +4.0 mA	8 8
V_{OL2}	Output Low Voltage	4.5V 5.5V		1.2 1.2	0.5 0.5	V V	I_{OL} = + 12 mA I_{OL} = + 12 mA	8 8
V_{RH}	Reset Input High Voltage	3.5V 5.5V	.8 V_{CC} .8 V_{CC}	V_{CC} V_{CC}	1.7 2.1	V V		13 13
V_{OLR}	Reset Output Low Voltage	3.5V 5.5V		0.6 0.6	0.3 0.2	V V	I_{OL} = 1.0 mA I_{OL} = 1.0 mA	13 13
V_{OFFSET}	Comparator Input Offset Voltage	4.5V 5.5V		25 25	10 10	mV mV		
V_{ICR}	Input Common Mode Voltage Range	4.5V 5.5V	0 0	V_{CC}-1.5V V_{CC}-1.5V		V V		10 10
I_{IL}	Input Leakage	4.5V 5.5V	-1 -1	2 2	<1 <1	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	4.5V 5.5V	-1 -1	2 2	<1 <1	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	
I_{IR}	Reset Input Current	4.5V 5.5V	-18 -18	-180 -180	-112 -112	µA µA		
I_{CC}	Supply Current	4.5V 5.5V		25 25	20 20	mA mA	@ 16 MHz @ 16 MHz	4,5 4,5
I_{CC1}	Standby Current Halt Mode	4.5V 5.5V		8 8	3.7 3.7	mA mA	V_{IN} = 0V, V_{CC} @ 16 MHz V_{IN} = 0V, V_{CC} @ 16 MHz	4,5 4,5
I_{CC2}	Standby Current (Stop Mode)	4.5V 5.5V		10 10	2 3	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	6,11,14 6,11,14
I_{ALL}	Auto Latch Low Current	4.5V 5.5V	1.4 1.4	20 20	4.7 4.7	µA µA	0V < V_{IN} < V_{CC} 0V < V_{IN} < V_{CC}	9 9

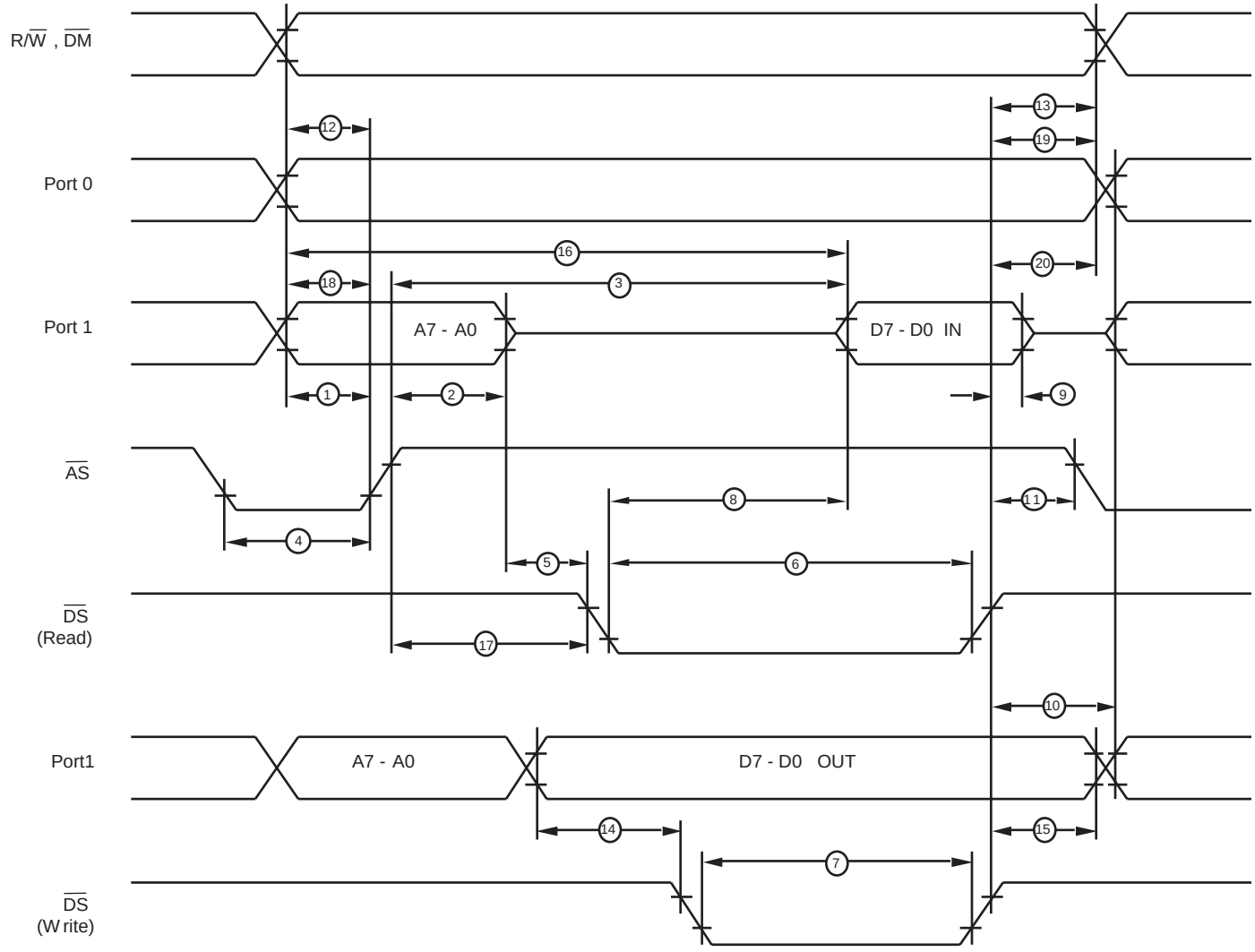


Figure 14. External I/O or Memory Read/Write Timing
Z86E40 Only

DC ELECTRICAL CHARACTERISTICS (Continued)

				T_A = 0°C to 70°C 16 MHz			
No	Symbol	Parameter	Note [3] V_{CC}	Min	Max	Units	Notes
1	TdA(AS)	Address Valid to $\overline{AS}$ Rise Delay	3.5V 5.5V	25 25		ns ns	2
2	TdAS(A)	$\overline{AS}$ Rise to Address Float Delay	3.5V 5.5V	35 35		ns ns	2
3	TdAS(DR)	$\overline{AS}$ Rise to Read Data Req'd Valid	3.5V 5.5V		180 180	ns ns	1,2
4	TwAS	$\overline{AS}$ Low Width	3.5V 5.5V	40 40		ns ns	2
5	TdAS(DS)	Address Float to $\overline{DS}$ Fall	3.5V 5.5V	0 0		ns ns	
6	TwDSR	$\overline{DS}$ (Read) Low Width	3.5V 5.5V	135 135		ns ns	1,2
7	TwDSW	$\overline{DS}$ (Write) Low Width	3.5V 5.5V	80 80		ns ns	1,2
8	TdDSR(DR)	$\overline{DS}$ Fall to Read Data Req'd Valid	3.5V 5.5V		75 75	ns ns	1,2
9	ThDR(DS)	Read Data to $\overline{DS}$ Rise Hold Time	3.5V 5.5V	0 0		ns ns	2
10	TdDS(A)	$\overline{DS}$ Rise to Address Active Delay	3.5V 5.5V	50 50		ns ns	2
11	TdDS(AS)	$\overline{DS}$ Rise to $\overline{AS}$ Fall Delay	3.5V 5.5V	35 35		ns ns	2
12	TdR/W(AS)	R/$\overline{W}$ Valid to $\overline{AS}$ Rise Delay	3.5V 5.5V	25 25		ns ns	2
13	TdDS(R/W)	$\overline{DS}$ Rise to R/$\overline{W}$ Not Valid	3.5V 5.5V	35 35		ns ns	2
14	TdDW(DSW)	Write Data Valid to $\overline{DS}$ Fall (Write) Delay	3.5V 5.5V	55 55	25 25	ns ns	2
15	TdDS(DW)	$\overline{DS}$ Rise to Write Data Not Valid Delay	3.5V 5.5V	35 35		ns ns	2
16	TdA(DR)	Address Valid to Read Data Req'd Valid	3.5V 5.5V		230 230	ns ns	1,2
17	TdAS(DS)	$\overline{AS}$ Rise to $\overline{DS}$ Fall Delay	3.5V 5.5V	45 45		ns ns	2
18	TdDM(AS)	$\overline{DM}$ Valid to $\overline{AS}$ Fall Delay	3.5V 5.5V	30 30		ns ns	2
20	ThDS(AS)	$\overline{DS}$ Valid to Address Valid Hold Time	3.5V 5.5V	35 35		ns ns	

Notes:

1. When using extended memory timing, add 2 TpC.
2. Timing numbers given are for minimum TpC.
3. The V_{CC} voltage specification of 5.5V guarantees 5.0V ±0.5V and the V_{CC} voltage specification of 3.5V guarantees only 3.5V

Standard Test Load

All timing references use 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.

For Standard Mode (not Low-EMI Mode for outputs) with SMR D1 = 0, D0 = 0.

Additional Timing Table (Divide-By-One Mode)

				T_A = 0 °C to +70 °C		T_A = -40 °C to +105 °C			
				4 MHz		4 MHz			
No	Symbol	Parameter	V_{CC} Note [6]	Min	Max	Min	Max	Units	Notes
1	TpC	Input Clock Period	3.5V	250	DC	250	DC	ns	1,7,8
			5.5V	250	DC	250	DC	ns	1,7,8
2	TrC,TfC	Clock Input Rise & Fall Times	3.5V		25		25	ns	1,7,8
			5.5V		25		25	ns	1,7,8
3	TwC	Input Clock Width	3.5V	100		100		ns	1,7,8
			5.5V	100		100		ns	1,7,8
4	TwTinL	Timer Input Low Width	3.5V	100		100		ns	1,7,8
			5.5V	70		70		ns	1,7,8
5	TwTinH	Timer Input High Width	3.5V	5TpC		5TpC			1,7,8
			5.5V	5TpC		5TpC			1,7,8
6	TpTin	Timer Input Period	3.5V	8TpC		8TpC			1,7,8
			5.5V	8TpC		8TpC			1,7,8
7	TrTin, TfTin	Timer Input Rise & Fall Timer	3.5V		100		100	ns	1,7,8
			5.5V		100		100	ns	1,7,8
8A	TwIL	Int. Request Low Time	3.5V	100		100		ns	1,2,7,8
			5.5V	70		70		ns	1,2,7,8
8B	TwIL	Int. Request Low Time	3.5V	5TpC		5TpC			1,3,7,8
			5.5V	5TpC		5TpC			1,3,7,8
9	TwIH	Int. Request Input High Time	3.5V	5TpC		5TpC			1,2,7,8
			5.5V	5TpC		5TpC			1,2,7,8
10	Twsm	STOP Mode Recovery Width Spec	3.5V	12		12		ns	4,8
			5.5V	12		12		ns	4,8
11	Tost	Oscillator Startup Time	3.5V		5TpC		5TpC		4,8,9
			5.5V		5TpC				

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request via Port 3 (P31–P33).
3. Interrupt request via Port 3 (P30).
4. SMR-D5 = 1, POR STOP Mode Delay is on.
5. Reg. WDTMR.
6. The V_{CC} voltage specification of 5.5V guarantees 5.0V ± 0.5V and the V_{CC} voltage specification of 3.5V guarantees 3.5V only.
7. SMR D1 = 0.
8. Maximum frequency for internal system clock is 4 MHz when using XTAL divide-by-one mode.
9. For RC and LC oscillator, and for oscillator driven by clock driver.

Additional Timing Table

				T_A = -40 °C to +105 °C 16 MHz				
No	Symbol	Parameter	V_{CC} Note [6]	Min	Max	Units	Conditions	Notes
1	TpC	Input Clock Period	3.5V	62.5	DC	ns		1,7,8
			5.5V	62.5	DC	ns		1,7,8
2	TrC,TfC	Clock Input Rise & Fall Times	3.5V		15	ns		1,7,8
			5.5V		15	ns		1,7,8
3	TwC	Input Clock Width	3.5V	31		ns		1,7,8
			5.5V	31		ns		1,7,8
4	TwTinL	Timer Input Low Width	3.5V	70		ns		1,7,8
			5.5V	70		ns		1,7,8
5	TwTinH	Timer Input High Width	3.5V	5TpC				1,7,8
			5.5V	5TpC				1,7,8
6	TpTin	Timer Input Period	3.5V	8TpC				1,7,8
			5.5V	8TpC				1,7,8
7	TrTin, TfTin	Timer Input Rise & Fall Timer	3.5V		100	ns		1,7,8
			5.5V		100	ns		1,7,8
8A	TwIL	Int. Request Low Time	3.5V	70		ns		1,2,7,8
			5.5V	70		ns		1,2,7,8
8B	TwIL	Int. Request Low Time	3.5V	5TpC				1,3,7,8
			5.5V	5TpC				1,3,7,8
9	TwIH	Int. Request Input High Time	3.5V	5TpC				1,2,7,8
			5.5V					
10	Twsm	STOP Mode Recovery Width Spec	3.5V	12		ns		4,8
			5.5V	12		ns		4,8
11	Tost	Oscillator Startup Time	3.5V		5TpC			4,8
			5.5V		5TpC			4,8
12	Twdt	Watch-Dog Timer Delay Time Before Timeout	3.5V	10		ms	D0 = 0	5,11
			5.5V	5		ms	D1 = 0	5,11
			3.5V	20		ms	D0 = 1	5,11
			5.5V	10		ms	D1 = 0	5,11
			3.5V	40		ms	D0 = 0	5,11
			5.5V	20		ms	D1 = 1	5,11
			3.5V	160		ms	D0 = 1	5,11
			5.5V	80		ms	D1 = 1	5,11

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request via Port 3 (P31–P33)
3. Interrupt request via Port 3 (P30)
4. SMR-D5 = 1, POR STOP Mode Delay is on
5. Reg. WDTMR
6. The V_{CC} voltage spec. of 5.5V guarantees 5.0V ± 0.5V.
7. SMR D1 = 0
8. Maximum frequency for internal system clock is 4 MHz when using XTAL divide-by-one mode.
9. For RC and LC oscillator, and for oscillator driven by clock driver.
10. Standard Mode (not Low EMI output ports)
11. Using internal RC

PIN FUNCTIONS

EPROM Programming Mode

D7–D0 Data Bus. The data can be read from or written to external memory through the data bus.

A11–A0 Address Bus. During programming, the EPROM address is written to the address bus.

V_{CC} Power Supply. This pin must supply 5V during the EPROM read mode and 6V during other modes.

$\overline{CE}$ Chip Enable (active Low). This pin is active during EPROM Read Mode, Program Mode, and Program Verify Mode.

$\overline{OE}$ Output Enable (active Low). This pin drives the direction of the Data Bus. When this pin is Low, the Data Bus is output, when High, the Data Bus is input.

EPM EPROM Program Mode. This pin controls the different EPROM Program Mode by applying different voltages.

V_{PP} Program Voltage. This pin supplies the program voltage.

$\overline{PGM}$ Program Mode (active Low). When this pin is Low, the data is programmed to the EPROM through the Data Bus.

Application Precaution

The production test-mode environment may be enabled accidentally during normal operation if excessive noise surges above V_{CC} occur on pins XTAL1 and $\overline{RESET}$.

In addition, processor operation of Z8 OTP devices may be affected by excessive noise surges on the V_{PP}, $\overline{CE}$, $\overline{EPM}$, $\overline{OE}$ pins while the microcontroller is in Standard Mode.

Recommendations for dampening voltage surges in both test and OTP mode include the following:

- Using a clamping diode to V_{CC}
- Adding a capacitor to the affected pin

Standard Mode

XTAL Crystal 1 (time-based input). This pin connects a parallel-resonant crystal, ceramic resonator, LC, RC network, or external single-phase clock to the on-chip oscillator input.

XTAL2 Crystal 2 (time-based output). This pin connects a parallel-resonant crystal, ceramic resonator, LC, or RC network to the on-chip oscillator output.

R/$\overline{W}$ Read/Write (output, write Low). The R/$\overline{W}$ signal is Low when the CCP is writing to the external program or data memory (Z86E40 only).

$\overline{RESET}$ Reset (input, active Low). Reset will initialize the MCU. Reset is accomplished either through Power-On, Watch-Dog Timer reset, STOP-Mode Recovery, or external reset. During Power-On Reset and Watch-Dog Timer Reset, the internally generated reset drives the reset pin low for the POR time. Any devices driving the reset line must be open-drain in order to avoid damage from a possible conflict during reset conditions. Pull-up is provided internally. After the POR time, $\overline{RESET}$ is a Schmitt-triggered input.

To avoid asynchronous and noisy reset problems, the Z86E40 is equipped with a reset filter of four external clocks (4TpC). If the external reset signal is less than 4TpC in duration, no reset occurs. On the fifth clock after the reset is detected, an internal RST signal is latched and held for an internal register count of 18 external clocks, or for the duration of the external reset, whichever is longer. During the reset cycle, $\overline{DS}$ is held active Low while $\overline{AS}$ cycles at a rate of TpC/2. Program execution begins at location 000CH, 5–10 TpC cycles after $\overline{RESET}$ is released. For Power-On Reset, the reset output time is 5 ms. The Z86E40 does not reset WDTMR, SMR, P2M, and P3M registers on a STOP-Mode Recovery operation.

$\overline{ROMless}$ (input, active Low). This pin, when connected to GND, disables the internal ROM and forces the device to function as a Z86C90/C89 ROMless Z8. (Note that, when left unconnected or pulled High to V_{CC}, the device functions normally as a Z8 ROM version).

Note: When using in ROM Mode in High EMI (noisy) environment, the ROMless pins should be connected directly to V_{CC}.

Port 2 (P27–P20). Port 2 is an 8-bit, bidirectional, CMOS-compatible I/O port. These eight I/O lines can be configured under software control as an input or output, independently. All input buffers are Schmitt-triggered. Bits programmed as outputs can be globally programmed as either push-pull or open-drain. Low EMI output buffers can be globally programmed by the software. When used as an I/O port, Port 2 can be placed under handshake control.

In Handshake Mode, Port 3 lines P31 and P36 are used as handshake control lines. The handshake direction is determined by the configuration (input or output) assigned to bit 7 of Port 2 (Figure 20).

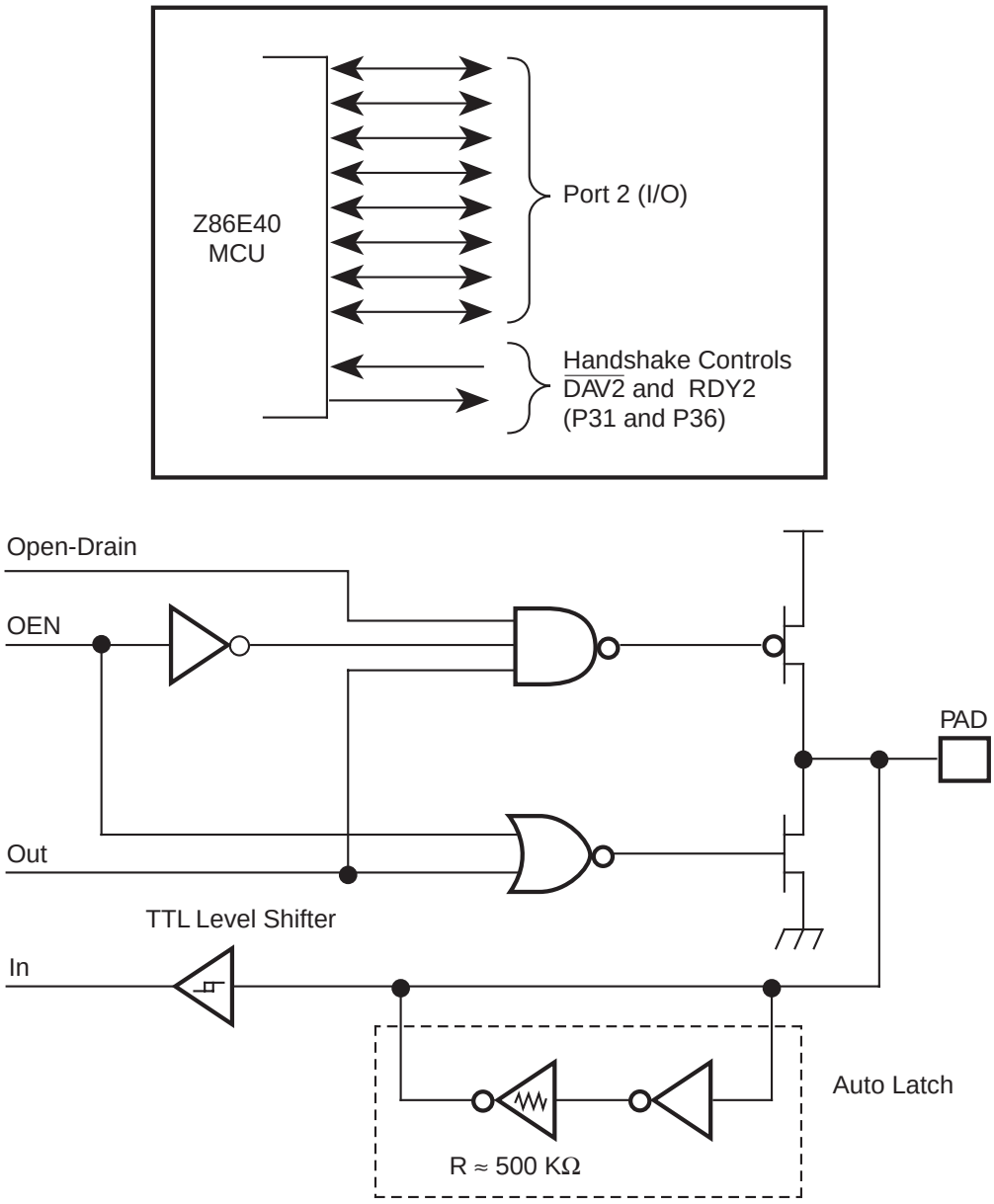


Figure 20. Port 2 Configuration

Register File. The register file consists of three I/O port registers, 236/125 general-purpose registers, 15 control and status registers, and three system configuration registers in the expanded register group. The instructions can access registers directly or indirectly through an 8-bit address field. This allows a short 4-bit register address using the Register Pointer (Figure 24). In the 4-bit mode, the register file is divided into 16 working register groups, each occupying 16 continuous locations. The Register Pointer addresses the starting location of the active working-register group.

Note: Register Bank E0–EF can only be accessed through working register and indirect addressing modes. (This bank is available in Z86E30/E40 only.)

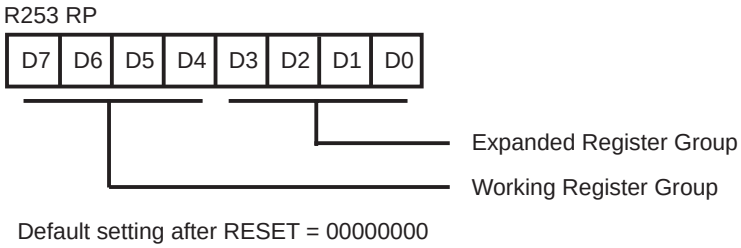


Figure 24. Register Pointer Register

Expanded Register File (ERF). The register file has been expanded to allow for additional system control registers, mapping of additional peripheral devices and input/output ports into the register address area. The Z8 register address space R0 through R15 is implemented as 16 groups of 16 registers per group (Figure 26). These register groups are known as the Expanded Register File (ERF).

The low nibble (D3–D0) of the Register Pointer (RP) select the active ERF group, and the high nibble (D7–D4) of register RP select the working register group. Three system configuration registers reside in the Expanded Register File at bank FH: PCON, SMR, and WDTMR. The rest of the Expanded Register is not physically implemented and is reserved for future expansion.

FUNCTIONAL DESCRIPTION (Continued)

Interrupts. The MCU has six different interrupts from six different sources. The interrupts are maskable and prioritized (Figure 28). The six sources are divided as follows: four sources are claimed by Port 3 lines P33–P30) and two in counter/timers. The Interrupt Mask Register globally or individually enables or disables the six interrupt requests (Table 10).

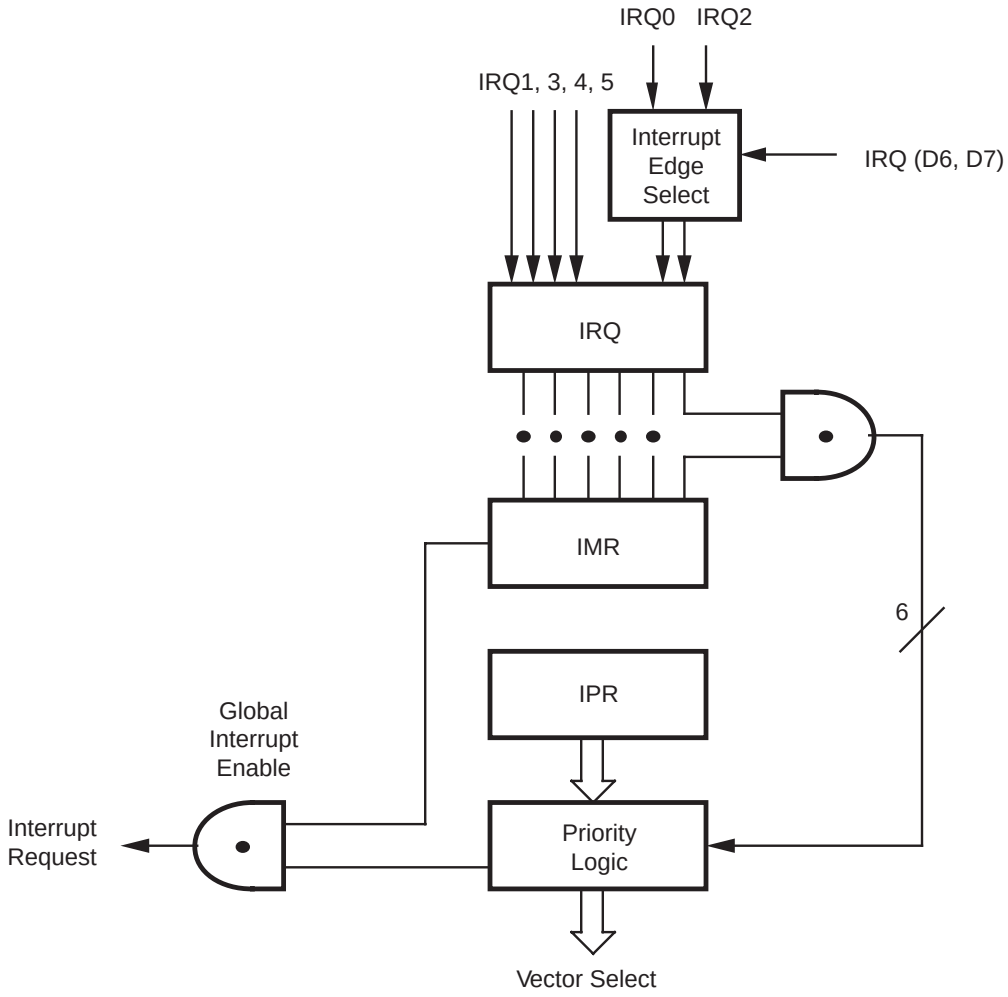


Figure 28. Interrupt Block Diagram

Table 10. Interrupt Types, Sources, and Vectors

Name	Source	Vector Location	Comments
IRQ0	$\overline{DAV0}$, IRQ0	0, 1	External (P32), Rising/Falling Edge Triggered
IRQ1	IRQ1	2, 3	External (P33), Falling Edge Triggered
IRQ2	$\overline{DAV2}$, IRQ2, T_{IN}	4, 5	External (P31), Rising/Falling Edge Triggered
IRQ3	IRQ3	6, 7	External (P30), Falling Edge Triggered
IRQ4	T0	8, 9	Internal
IRQ5	TI	10, 11	Internal

FUNCTIONAL DESCRIPTION (Continued)

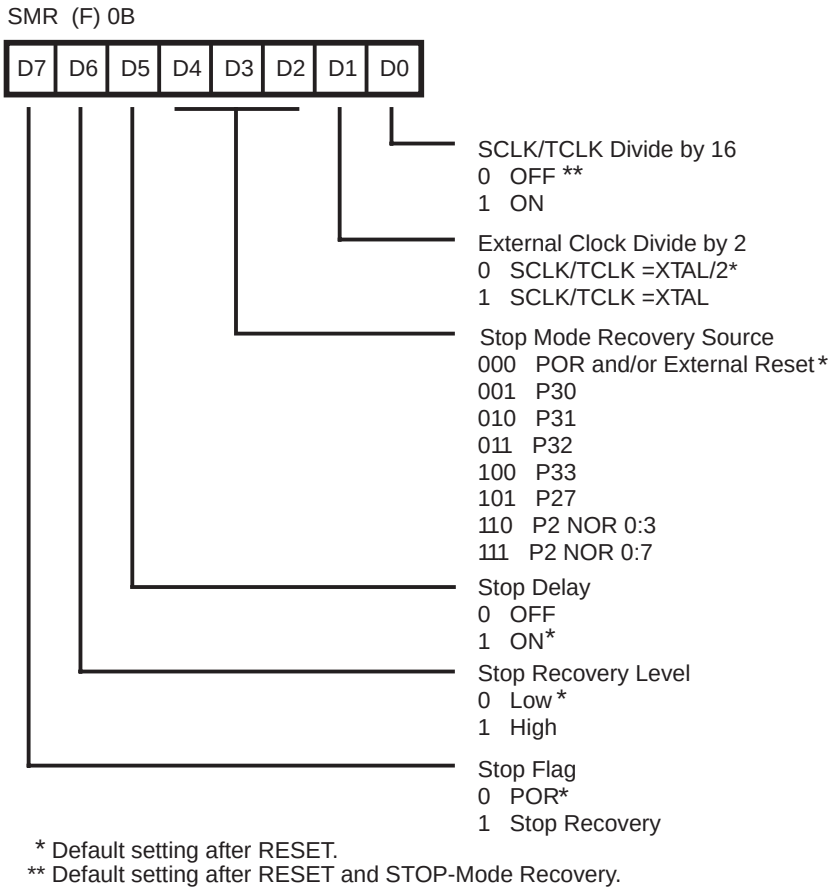
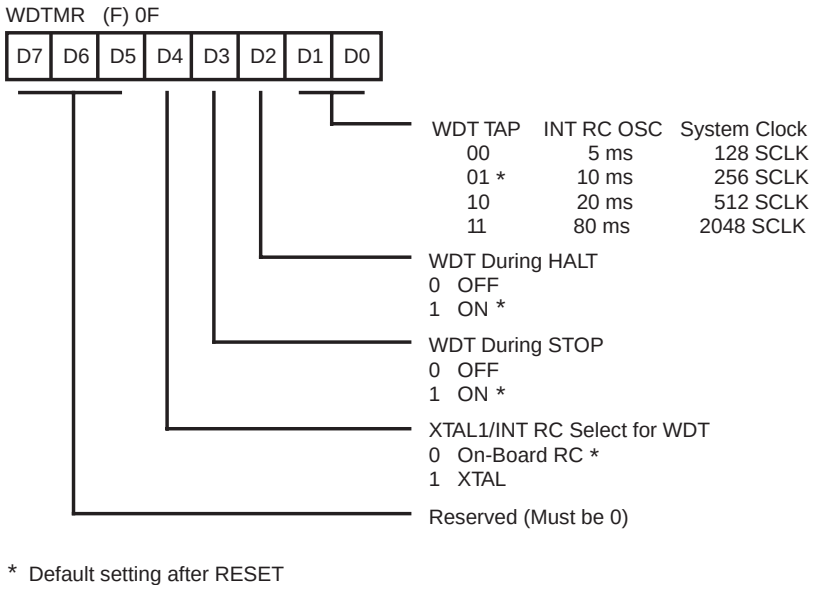


Figure 31. STOP-Mode Recovery Register (Write-Only Except Bit D7, Which is Read-Only)

cycles from the execution of the first instruction after Power-On Reset, Watch-Dog reset or a STOP-Mode Recovery (Figures 33 and 34). After this point, the register cannot be modified by any means, intentional or otherwise. The WDTMR cannot be read and is located in Bank F of the Expanded Register Group at address location 0FH.



* Default setting after RESET

Figure 33. Watch-Dog Timer Mode Register Write Only

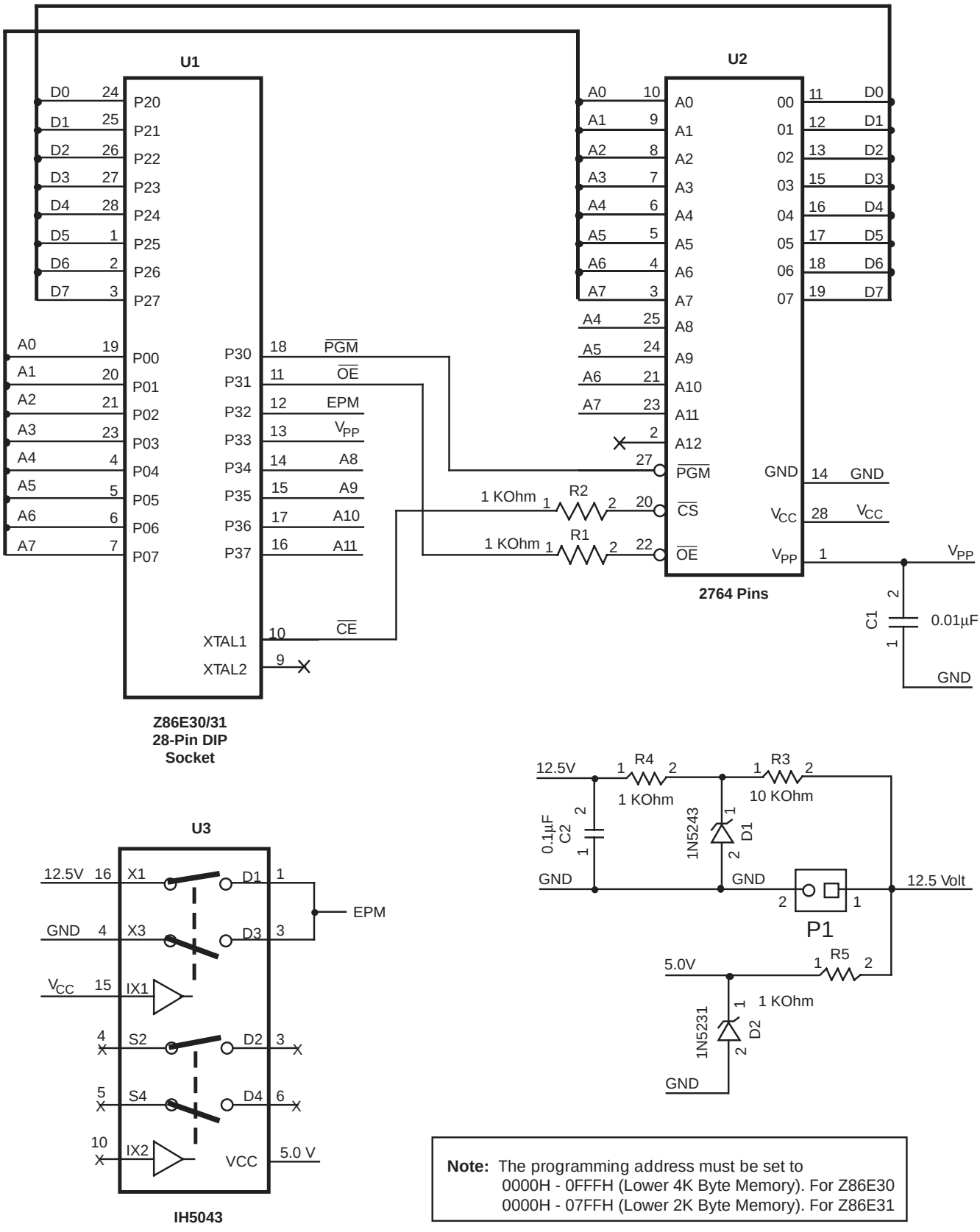


Figure 39. Z86E30/E31 Programming Adapter Circuitry

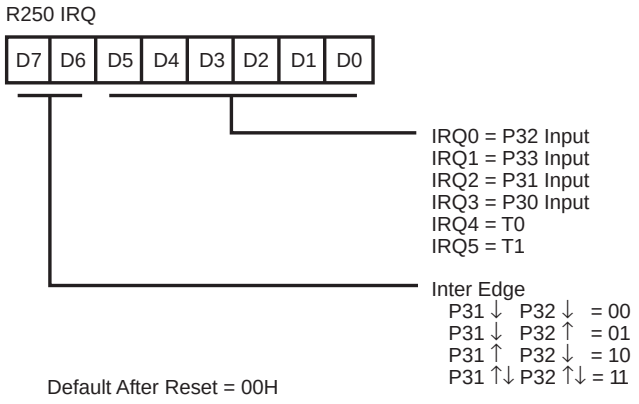
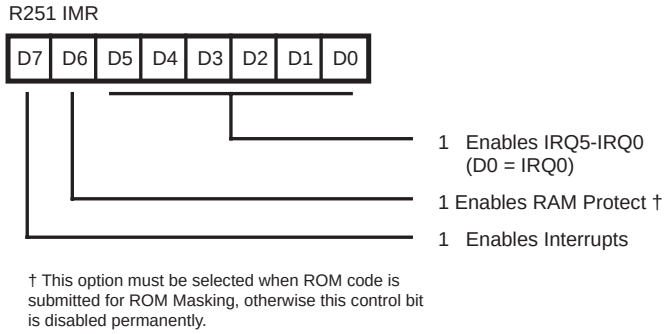


Figure 55. Interrupt Request Register
FAH: Read/Write



† This option must be selected when ROM code is submitted for ROM Masking, otherwise this control bit is disabled permanently.

Figure 56. Interrupt Mask Register
FBH: Read/Write

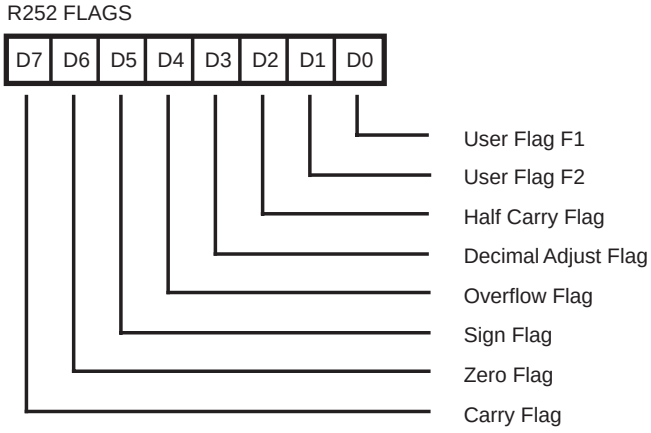


Figure 57. Flag Register
FCH: Read/Write

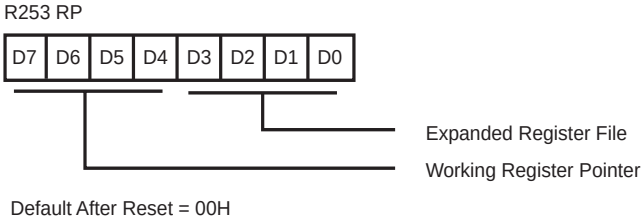


Figure 58. Register Pointer
FDH: Read/Write

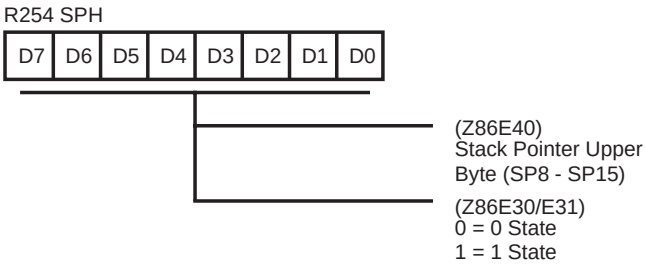


Figure 59. Stack Pointer High
FEH: Read/Write

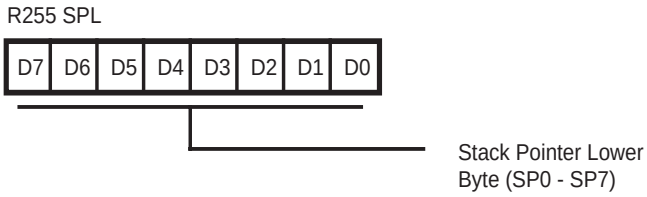
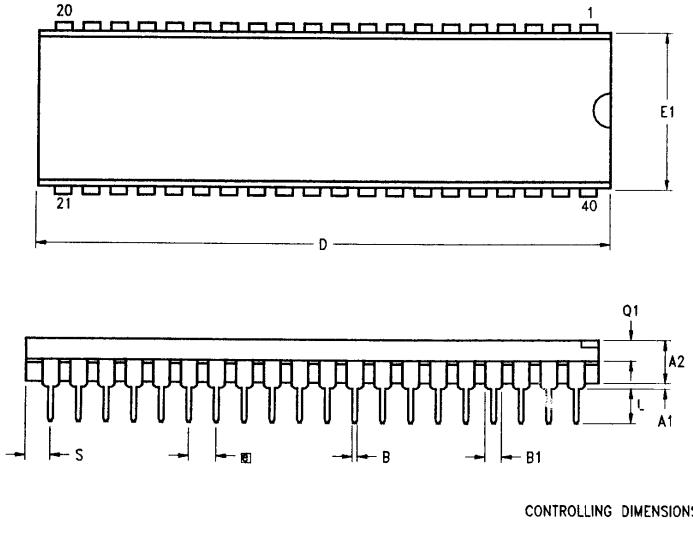


Figure 60. Stack Pointer Low
FFH: Read/Write

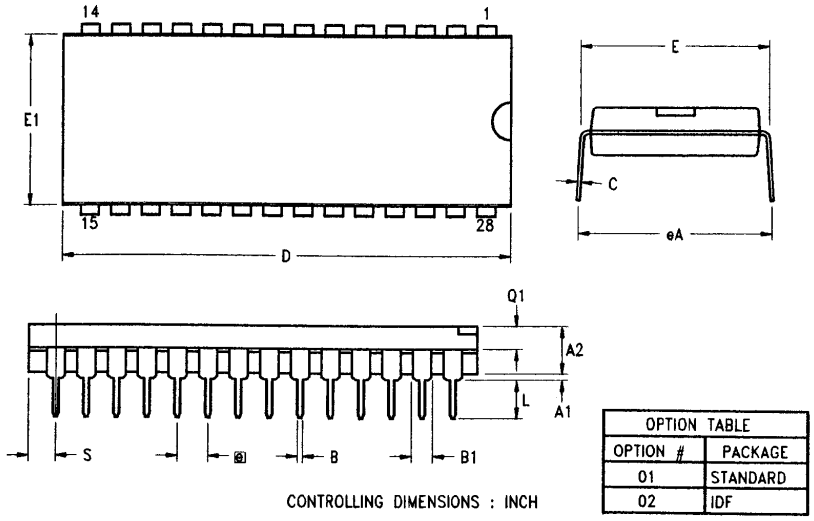
PACKAGE INFORMATION (Continued)

PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	1.02	.020	.040
A2	3.18	3.94	.125	.155
B	0.38	0.53	.015	.021
B1	1.02	1.52	.040	.060
C	0.23	0.38	.009	.015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
e	2.54 TYP		.100 TYP	
eA	15.49	16.76	.610	.660
L	3.05	3.81	.120	.150
Q1	1.52	1.91	.060	.075
S	1.52	2.29	.060	.090

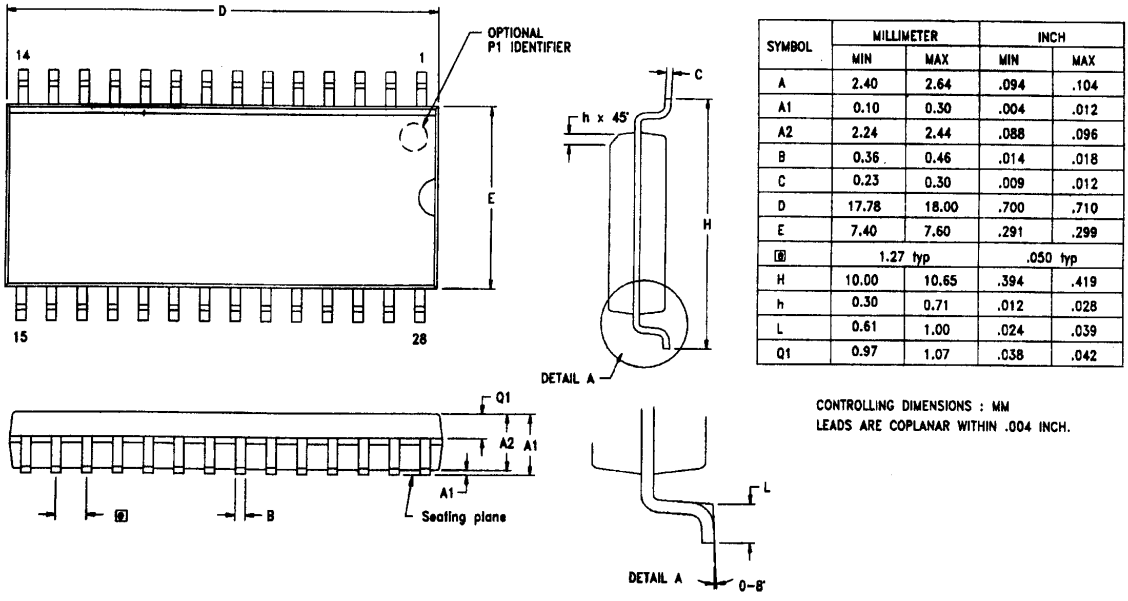
Figure 61. 40-Pin DIP Package Diagram



OPTION TABLE	
OPTION #	PACKAGE
01	STANDARD
02	IDF

SYMBOL	OPT #	MILLIMETER		INCH	
		MIN	MAX	MIN	MAX
A1		0.51	1.02	.020	.040
A2		3.18	3.94	.125	.155
B		0.38	0.53	.015	.021
B1	01	1.40	1.65	.055	.065
	02	1.14	1.40	.045	.055
C		0.23	0.38	.009	.015
D	01	36.58	37.34	1.440	1.470
	02	35.31	35.94	1.390	1.415
E		15.24	15.75	.600	.620
E1	01	13.59	14.10	.535	.555
	02	12.83	13.08	.505	.515
e		2.54 TYP		.100 TYP	
eA		15.49	16.76	.610	.660
L		3.05	3.81	.120	.150
Q1	01	1.52	1.91	.060	.075
	02	1.52	1.78	.060	.070
S	01	1.52	2.29	.060	.090
	02	1.02	1.52	.040	.060

Figure 64. 28-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.64	.094	.104
A1	0.10	0.30	.004	.012
A2	2.24	2.44	.088	.096
B	0.36	0.46	.014	.018
C	0.23	0.30	.009	.012
D	17.78	18.00	.700	.710
E	7.40	7.60	.291	.299
e	1.27 typ		.050 typ	
H	10.00	10.65	.394	.419
h	0.30	0.71	.012	.028
L	0.61	1.00	.024	.039
Q1	0.97	1.07	.038	.042

Figure 65. 28-Pin SOIC Package Diagram